

MATERIAL DECLARATION SHEET



Material Number	SF-0402FP-F			
Product Line	Lead Free Thin Film Chip Fuse			
Compliance Date	08/30/2017			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Body Copper Layer (Fuselink)	Copper Clad Laminate (FR4)	0.16522	Carbon	7440-44-0	40.98%	16.06%	39.197%
				Oxygen	7782-44-7	35.92%	14.08%	
				Silicon	7440-21-3	18.11%	7.10%	
				Hydrogen	1333-74-0	3.73%	1.46%	
				Aluminum	7429-90-5	0.26%	0.10%	
				Calcium	7440-70-2	0.36%	0.14%	
				Copper	7440-50-8	0.65%	0.25%	
2	Tin Layer (Fuselink)	Tin	0.00020	Tin	7440-31-5	100%	0.05%	0.047%
3	Copper Layer (Termination)	Copper	0.10546	Copper	7440-50-8	100%	25.02%	25.02%
4	Plating	Nickel	0.06377	Nickel	7440-02-0	100.00%	8.32%	15.129%
		Tin		Tin	7440-31-5	100.00%	6.81%	
5	Cover	Soldermask Ink	0.07996	Carbon	7440-44-0	31.37%	5.95%	18.970%
				Oxygen	7782-44-7	36.70%	6.96%	
				Titanium	7440-32-6	8.83%	1.68%	
				Barium	7440-39-3	3.31%	0.63%	
				Hydrogen	1333-74-0	6.84%	1.30%	
				Silicon	7440-21-3	3.82%	0.73%	
				Magnesium	7439-95-4	7.23%	1.37%	
				Sulfur	7704-34-9	0.77%	0.15%	
Nitrogen	7727-37-9	1.12%	0.21%					

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6	Marking Code	Marking ink	0.00690	Carbon	7440-44-0	33.81%	0.56%	1.637%
				Oxygen	7782-44-7	39.56%	0.66%	
				Titanium	7440-32-6	9.52%	0.16%	
				Barium	7440-39-3	3.57%	0.06%	
				Hydrogen	1333-74-0	7.38%	0.12%	
				Silicon	7440-21-3	4.12%	0.07%	
				Sulfur	7704-34-9	0.83%	0.01%	
				Nitrogen	7727-37-9	1.20%	0.02%	
		Total weight	0.42151					

This Document was updated on: 8-30-17

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.